

# PATENT ABSTRACTS OF JAPAN

(11)Publication number : 2001-323037

(43)Date of publication of application : 20.11.2001

(51)Int.Cl.

C08G 8/28

C08G 59/62

G03F 7/004

G03F 7/038

H01L 21/027

(21)Application number : 2000-138977

(71)Applicant : INST OF PHYSICAL & CHEMICAL  
RES

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(22)Date of filing : 11.05.2000

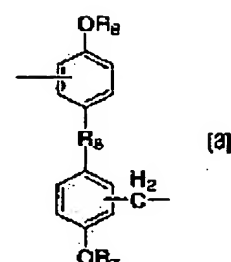
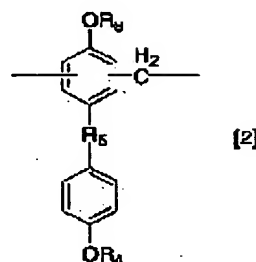
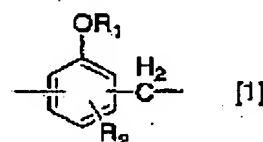
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## (54) PHOTOCURABLE AND THERMOSETTING RESIN COMPOSITION

### (57)Abstract:

**PROBLEM TO BE SOLVED:** To provide a photosensitive resin composition capable of developing in an alkaline aqueous solution, processing at a low temperature and giving an excellent heat-resistant resin layer, and a phenol novolak useful as a curing agent for such resin composition.

**SOLUTION:** The invention discloses a phenol novolak comprising a structural unit represented by general formula [1] and having an organic group consisting of a cis-diene structure as a part of R1 and 3-30 of average degree of polymerization; a phenol novolak which is represented by general formulas [2] and [3], one or both of R3 and R4 and one or both of R6 and R7 are an organic group having a cis-diene structure and average degree of polymerization is 2-25; and a photocurable and thermosetting resin composition containing (a) a polyfunctional epoxy resin, (b) the above-mentioned phenol novolak and (c) an oxygen sensitizer.



## LEGAL STATUS

[Date of request for examination]

[Date of sending the examiner's decision of rejection]

[Kind of final disposal of application other than the examiner's decision of rejection or application converted registration]

[Date of final disposal for application]

[Patent number]

[Date of registration]

[Number of appeal against examiner's decision of rejection]

[Date of requesting appeal against examiner's  
decision of rejection]

[Date of extinction of right]

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